

# HZM6.2ZMWA

## Silicon Planar Zener Diode for Surge Absorb

REJ03G1208-0100 (Previous: ADE-208-1514)

Rev.1.00

Jun 08, 2005

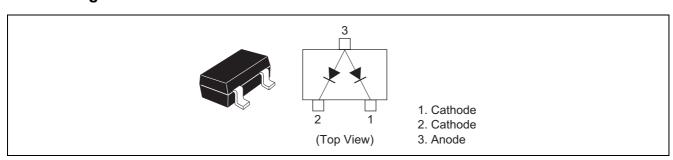
### **Features**

- HZM6.2ZMWA has two devices in a monolithic, and can absorb surge.
- Low capacitance (C = 8.5 pF max) and can protect ESD of signal line.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

### **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HZM6.2ZMWA	62N	MPAK	PLSP0003ZC-A (MPAK)

### **Pin Arrangement**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Power dissipation	Pd *1	200	mW
Junction temperature	Тј	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. Two device total, See Fig.2.

## Electrical Characteristics \*1

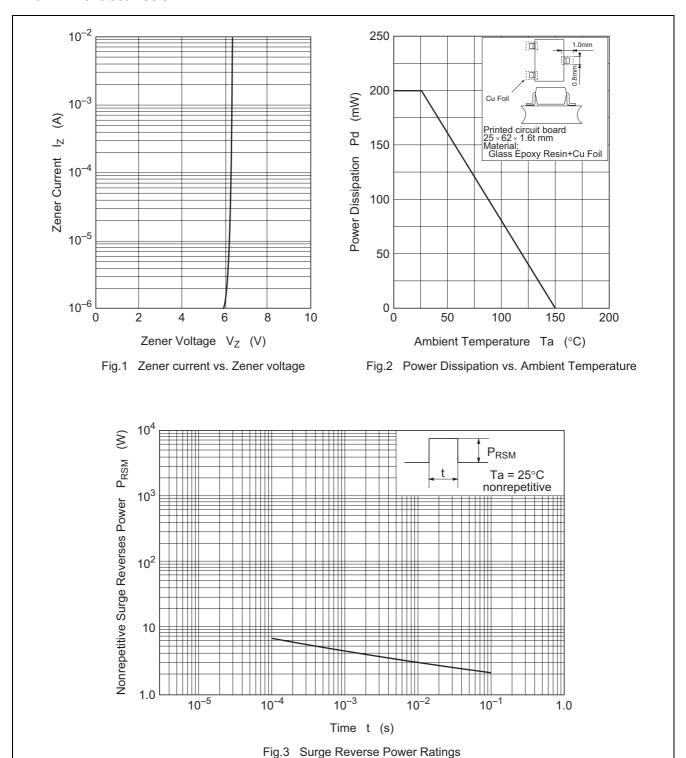
 $(Ta = 25^{\circ}C)$ 

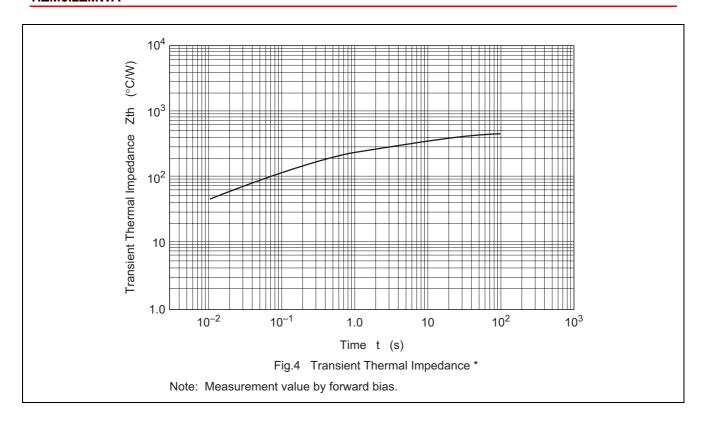
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	5.90	_	6.50	V	$I_Z$ = 5 mA, 40 ms pulse
Reverse current	I <sub>R</sub>	_	_	3	μΑ	V <sub>R</sub> = 5.5 V
Capacitance	С	_	_	8.5	pF	V <sub>R</sub> = 0 V, f = 1 MHz
Dynamic resistance	r <sub>d</sub>	_	_	60	Ω	$I_Z = 5 \text{ mA}$
ESD-Capability *2	_	13	_	_	kV	C = 150 pF, R = 330 $\Omega$ , Both forward and reverse direction 10 pulse

Notes: 1. Per one device

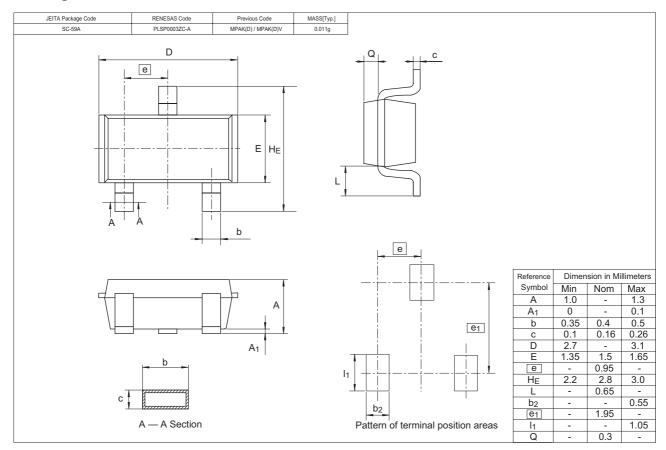
2. Failure criterion ;  $I_R > 3~\mu\text{A}$  at  $V_R$  = 5.5 V.

### **Main Characteristic**





### **Package Dimensions**



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